

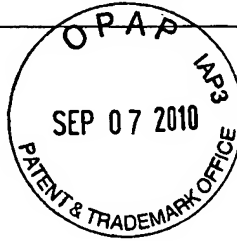
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kazumasa TANIDA et al.

Application No.: 10/594,561

Filed: September 27, 2006

For: SEMICONDUCTOR DEVICE WITH A
SEMICONDUCTOR CHIP CONNECTED IN
A FLIP CHIP MANNER



Docket No.: AI 427NP

Confirmation No.: 5593

Art Unit: 2826

Examiner: Teresa M. Arroyo

INFORMATION DISCLOSURE STATEMENT (IDS)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is an Information Disclosure Statement submitted in compliance with the timing requirements of 37 C.F.R. § 1.97(b)(4), i.e. prior to a first Office Action on the merits after the filing of a request for continued examination under § 1.114.

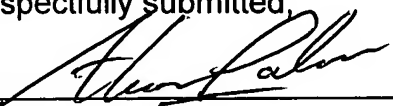
Listed for consideration on the attached PTO/SB/08 are the foreign references cited in a foreign Office Action issued on June 24, 2010. A copy of the foreign references and foreign Office Action with English translation are enclosed. Consideration of the listed documents is respectfully requested.

It is hereby certified that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in connection with a counterpart foreign application not more than three months prior to the filing of this statement.

Should any fee be required, however, the Commissioner is hereby authorized to charge such fee to our Deposit Account No. 18-0002 and notify us accordingly.

September 7, 2010
Date

Respectfully submitted,

By 
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ALP/pq